

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S4	330	(700/45).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 16:06
S5	1462	(700/121).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 16:41
S6	75	(700/172).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/16 11:32
S7	205	(700/225).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 16:18
S8	311	(700/37).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 16:22
S9	18	(700/205).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 16:05
S10	210	(700/299).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 16:21
S11	20927	feedback and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 16:41

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S12	186	feedback and wafer and exposure adj energy	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 16:42
S13	10	wafer and (exposure adj energy) same feedback	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 16:43
S14	6	wafer and (exposure adj energy) same feedback and (width or density or thick)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 16:45
S15	2	wafer and (exposure adj energy) same feedback and (width or density or thick) and poly-gate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 16:46
S16	2	wafer and (exposure adj energy) and feedback and (width or density or thick) and poly-gate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 16:46
S17	22	wafer and (exposure) and feedback and (width or density or thick) and poly-gate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 15:28
S23	3	wafer and (exposure) and feedback and (width or density or thick) and poly-gate and feedforward	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 15:34
S24	19	wafer and (exposure) and feedback and (width or density or thick) and poly-gate and error	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/17 12:51

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S28	867	wafer and (exposure) and feedback and ( polish or cmp)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/17 12:52
S29	851	wafer and (exposure) and feedback and ( polish or cmp) and (width or density or thickness)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/17 12:52
S31	770	wafer and (exposure) and feedback and ( polish or cmp) and (thickness)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/17 12:53
S32	15	wafer and (exposure adj energy) and feedback and ( polish or cmp) and (thickness)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/17 16:46
S42	444	(chemical adj mechanical adj planarization) and ((multi or muliple) adj3 layers)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/17 16:49
S43	283	(chemical adj mechanical adj planarization) and ((multi or muliple) adj3 layers) and ((fed adj "1" back) or feedback)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/17 20:56
S44	64	(chemical adj mechanical adj planarization) and ((multi or muliple) adj3 layers) and ((fed adj1 back) or feedback)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/17 16:53
S45	121	((chemical adj mechanical adj planarization) or cmp) and ((multi or muliple) adj3 layers) and ((fed adj1 back) or feedback) and exposure	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/17 16:57

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S48	19	((chemical adj mechanical adj planarization) or cmp) and ((multi or multiple) adj3 layers) and ((fed adj1 back) or feedback) and feed adj2 forward	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/17 17:06
S50	47	((chemical adj mechanical adj planarization) or cmp) and ((multi or multiple) adj3 layers) and ((fed adj1 back) or feedback) and ((feed adj2 forward) OR FEED ADJ FORWARD OR FEEDFORWARD OR FEDWARD) AND EXPOSURE	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/17 17:32
S57	6689	(chemical adj1 mechanical adj1 planarization)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/17 20:56
S58	922	(chemical adj1 mechanical adj1 planarization) and (multiple adj3 layers)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/17 20:57
S59	858	(chemical adj1 mechanical adj1 planarization) and (multiple adj3 layers) and ((semi adj1 conductor) or semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/17 20:57